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| | | Specific | ation |
|-------------|----------|--|---|
| P | art Numl | ber: MC21 | 605GL6W-SPTLY |
| V | ersion: | 1 | |
| D | Date: | 13/03/2 | 015 |
| | | Revis | ion |
| 0 A B | | 2011/12/26 2013/02/25 2014/12/02 | First issue Correct pin4=RS Modify Backlight Information Remove IC information |

design • manufacture • supply

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1.General Specification

The Features is described as follow:

- Module dimension: 80.0 x 36.0 x 13.2(max.) mm
- View area: 66.0 x 16.0 mm
- Active area: 56.20 x 11.5 mm
- Number of Characters: 16 characters x 2 Lines
- Dot size: 0.55 x 0.65 mm
- Dot pitch: 0.60 x 0.70 mm
- Character size: 2.95 x 5.55 mm
- Character pitch: 3.55 x 5.95 mm
- LCD type: STN Positive, Yellow Green Transflective
- Duty: 1/16
- View direction: 6 o'clock
- Backlight Type: Yellow Green
- Driver: RW1063 Manufacture Supply

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Midas LCD Part Number System

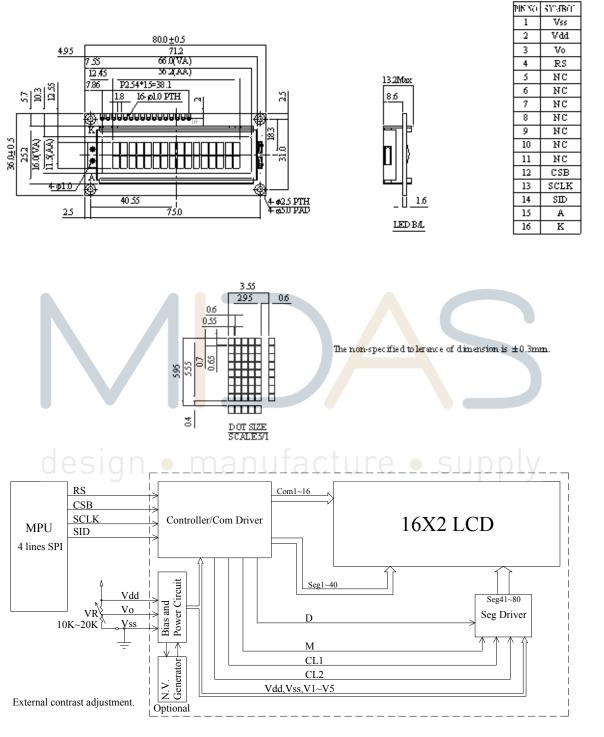
| MC | COG | 132033 | Α | * | 6 | w | * | * | - | S | Ν | Т | L | W | * | * |
|----|-----|--|---|--|--|--------------------------------|---|---|--|--------------|---------------|------------------|----------------|-----------------|-----------|----|
| 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | - | 10 | 11 | 12 | 13 | 14 | 15 | 16 |
| 1 | = | MC: Midas Con | nponer | nts | | | | | | | | | | | | |
| 2 | = | Blank: COB (ch | ip on l | ooard) | COG | : chip on | glass | | | | | | | | | |
| 3 | = | No of dots | | (e.g. 240 | 064 = 2 | 240 x 64 | dots) | (e.g. 21 | 605 = 2 | x 16 5n | nm C.H. |) | | | | |
| 4 | = | Series | | | | | | | | | | | | | | |
| 5 | = | Series Variant: | , | A to Z – | see ad | dendum | | | | | | | | | | |
| 6 | = | 3: 3 o'clock | (| 6: 6 o'cl | ock | 9 : 9 | 9 o'cloc | k | 12 : 1 | 2 o'cloc | k | | | | | |
| 7 | = | S : Normal (0 to | + 50 0 | deg C) | W: Wid | e temp. (| (-20 to | + 70 deg | g C) X | : Extend | ed temp | (-30 + 8 | 30 Deg (| 2) | | |
| 8 | = | Character Set | | | | | | | | | | | | | | |
| 9 | - | Blank 9.51 2 8.9 3 7.8 4 7.8 5 9.5 6 7 m 7 7 m 8 6.4 9 6.4 A 5.5 D 6.00 E 5.00 | plified g 5 (Gr d) (En lese (sp English) English/ where a p of Be mm / r mm mm mm mm mm mm mm mm mm m | (Graphic aphic D glish/Ger oecial) /Scandin /Greek) Scandina | c Displa isplays rman/Fr avian) avian/Icc avian/Icc avian/Icc avian/Icc | only) rench/Gro elandic) | on (via and 2) mon mon irate mon irate mon irate mon irate irate irate irate irate irate irate irate | Arra Edge Arr Arr Arr Arr Arr Ed Ed Ed Ed Ed Ed Ed | e Lit ray ray ray ray ray ge ge ge ge ge ge ge ge | | | S | | | y | |
| 10 | = | T: TN S : STN | B: STN | N Blue C | G: STN | Grey F : | FSTN I | F2: FFS1 | ΓΝ Ζ: 2 | Zero Pov | ver (Bi-S | table) | | | | |
| 11 | = | P: Positive N: N | Vegativ | re | | | | | | | | | | | | |
| 12 | = | R: Reflective M | : Tran | smissive | T: Tra | insflective | e | | | | | | | | | |
| 13 | = | Backlight: Blan | k: Refle | ective L | : LED | | | | | | | | | | | |
| 14 | = | Backlight Colou | r: ` | Y: Yellow | v-Green | W: Wh | ite B: E | Blue R: | Red A | Amber | 0: Ora | inge G: C | Green R | GB: R.G. | B. | |
| | | If Z (Zero Powe | er): ' | WB: Wh | ite on b | olue GB | : Green | on blac | ck YB: | Yellow | on black | ΥΡΒ: Υ | ellow on | ı pink ar | ıd/or blu | e |
| 15 | = | Driver Chip: | 1 | Blank: St | tandard |]: ŀ | ст: | Toshiba | n T6963 | BC A: | Avant S | AP1024B | R: R | aio RA88 | 835 | |
| 16 | = | Voltage Variant | :: e.g. 3 | s = 3v | | | | | | | | | | | | |
| | | | | | | | | | | | 4.r.1 .r. | 1001 - | | | | |

F/Displays/Midas Brand/Midas LCD Part Number System 2 March 2011.doc

3.Interface Pin Function

| Pin No. | Symbol | Level | Description |
|---------|--------|------------|--|
| 1 | Vss | 0V | Ground |
| 2 | Vdd | 5.0V | Supply Voltage for logic |
| 3 | VO | (Variable) | Operating voltage for LCD |
| 4 | RS | _ | In bus mode, used as register selection input. When RS = "High", Date register is selected. When RS = "Low", Instruction register is selected. |
| 5 | NC | | No connection |
| 6 | NC | _ | No connection |
| 7 | NC | _ | No connection |
| 8 | NC | - | No connection |
| 9 | NC | - | No connection |
| 10 | NC | - | No connection |
| 11 | NC | ian - | No connection |
| 12 | CSB | H/L | In 4-SPI serial mode, used as chip selection input. When CSB = "Low", selected When CSB = "High", not selected. (Low access enable) |
| 13 | SCLK | H/L | Serial clock input |
| 14 | SID | H/L | Serial data input |
| 15 | А | | Power supply for B/L + |
| 16 | К | | Power supply for B/L - |

4.Contour Drawing &Block Diagram



| Character located | - | 2 | 0 | | • | ~ | ' | 0 | | | | | | · · | | 10 |
|-------------------|----|----|----|----|----|----|----|----|----|----|----|----|----|-----|----|----|
| DDRAM address | 00 | 01 | 02 | 03 | 04 | 05 | 06 | 07 | 08 | 09 | 0A | 0B | 0C | 0D | 0E | 0F |
| DDRAM address | 40 | 41 | 42 | 43 | 44 | 45 | 46 | 47 | 48 | 49 | 4A | 4B | 4C | 4D | 4E | 4F |

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5.Character Generator ROM Pattern

Table.2

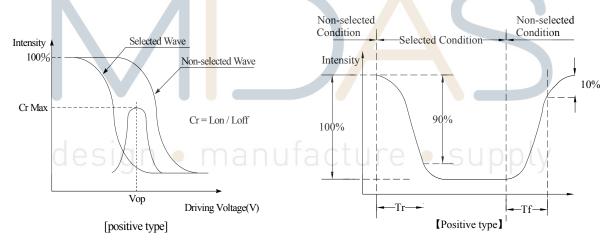
| <u>b7≈4</u> b3≈0 | 0000 | 0001 | 0010 | 0011 | 0100 | 010 1 | 0110 | 0111 | 1000 | 1001 | 1010 | 1011 | 1100 | 110 1 | 1110 | 1111 |
|---------------------|-------------------|------|------|------|------|--------------|------|------|------|------|------|------|------|--------------|------|------|
| 0000 | [00] | | | | | | | | | | | | | | | |
| 0001 | CG RAM [01] | | | | | | | | | | | | | | | |
| 0010 | CG RAM [02] | | | | | | | | | | | | | | | |
| 0011 | CG RAM [03] | | | | | | | | | | | | | | | |
| 0100 | CG RAM [04] | | | | | | | | | | | | | | | |
| 0101 | CG RAM [05] | | | | | | | | | | | | | | | |
| 0110 | CG RAM [06] | | | | | | | Q | | | | | | | | |
| 0111 | CG RAM [07] | | | | | | | W | | | | | | | | |
| 1000 | CG RAM [00] | | | | | | | 8 | | | | | | | | |
| 1001 | СС RAM [01] | | | | | | | | | | | | | | | |
| 1010 | CG RAM [02] | | | | | | | | | | | | | | | |
| 1011 | CG RAM [03] | | | | | | | | | | | | | | | |
| 1100 | CG RAM [04] | | | | | | | | | | | | | | | |
| 1101 | сс кам [05] | | | | | | | | | | | | | | | |
| 1110 | сс кам [06] | | | | | | | | | | | | | | | |
| 1111 | СС КАМ [07] | | | | | | | | | | | | | | | |

6.Optical Characteristics

| Item | Symbol | Condition | Min | Тур | Max | Unit |
|----------------|--------|-----------|-----|-----|-----|---------|
| | θ | CR≧2 | 0 | _ | 20 | ψ= 180° |
| | θ | CR≧2 | 0 | — | 40 | ψ= 0° |
| View Angle | θ | CR≧2 | 0 | | 30 | ψ= 90° |
| | θ | CR≧2 | 0 | _ | 30 | ψ= 270° |
| Contrast Ratio | CR | _ | | 3 | | _ |
| | T rise | _ | | 150 | 200 | ms |
| Response Time | T fall | — | _ | 150 | 200 | ms |

Definition of Operation Voltage (Vop)

Definition of Response Time (Tr, Tf)



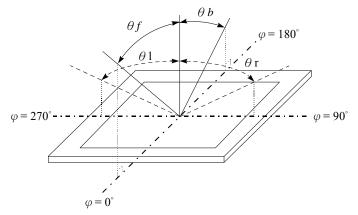
Conditions :

Operating Voltage : Vop Viewing

Viewing Angle(θ , ϕ) : 0° , 0°

Frame Frequency : 64 HZ Driving Waveform : 1/N duty , 1/a bias

Definition of viewing angle(CR≥2)



7.Absolute Maximum Ratings

| Item | Symbol | Min | Тур | Мах | Unit |
|--------------------------|---------|----------|-----|----------------------|------|
| Operating Temperature | Тор | -20 | _ | +70 | |
| Storage Temperature | Тѕт | -30 | _ | +80 | |
| Input Voltage | Vin | -0.3 | _ | V _{DD} +0.3 | V |
| Supply Voltage For Logic | VDD-Vss | -0.3 | _ | 5.5 | V |
| Supply Voltage For LCD | VDD-V0 | Vss -0.3 | _ | V _{SS} +7.0 | V |



8.Electrical Characteristics

| ltem | Symbol | Condition | Min | Тур | Max | Unit |
|--------------------------|---------------------------------|-----------------------|------|-----|-----------------|------|
| Supply Voltage For Logic | Vdd-Vss | _ | 4.5 | 5.0 | 5.5 | V |
| Supply Voltage For LCD | | Ta=-20 | _ | _ | 5.2 | V |
| *Note | V _{DD} -V ₀ | Ta=25 | 3.6 | 3.7 | 3.8 | V |
| | | Ta=70 | 3.2 | _ | _ | V |
| Input High Volt. | Vih | _ | 2.5 | | V _{DD} | V |
| Input Low Volt. | VIL | _ | -0.3 | | 0.55 | V |
| Output High Volt. | Vон | _ | 3.9 | | V _{DD} | V |
| Output Low Volt. | | | | _ | 0.4 | V |
| Supply Current | l <mark>o</mark> d | V _{DD} =5.0V | 1.0 | 1.2 | 1.5 | mA |

* Note: Please design the VOP adjustment circuit on customer's main board



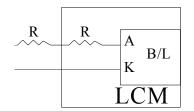
9.Backlight Information

Specification

| PARAMETER | SYMBOL | ΜΙΝ | ТҮР | MAX | UNIT | TEST CONDITION |
|----------------------------|-----------|-----|--------|-----|-------------------|-------------------------------------|
| Supply Current | ILED | 117 | 130 | 156 | mA | V=4.1V |
| Supply Voltage | v | 3.9 | 4.1 | 4.3 | v | _ |
| Reverse Voltage | VR | _ | _ | 8 | v | _ |
| Luminance (Without LCD) | IV | 216 | 270 | _ | CD/M ² | ILED=130mA |
| Wave Length | λр | 569 | 570 | 573 | nm | ILED=130mA |
| Life Time | - / | - | 100000 | | Hr. | ILED <i>≦</i> 130mA 25 ,50-60%RH |
| Color | Yellow Gr | een | | | | |

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

2.Drive from pin15,pin16



ill never get Vee output from pin15)

10.Reliability

Content of Reliability Test (Wide temperature, -20 ~70)

| | Environmental Test | | |
|---------------------------------------|---|--|------|
| Test Item | Content of Test | Test Condition | Note |
| High Temperature storage | Endurance test applying the high storage temperature for a long time. | 200hrs | 2 |
| Low Temperature storage | Endurance test applying the low storage temperature for a long time. | -30 200hrs | 1,2 |
| High Temperature Operation | Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time. | 70 200hrs | |
| Low Temperature Operation | Endurance test applying the electric stress under low temperature for a long time. | -20 200hrs | 1 |
| High Temperature/ Humidity storage | The module should be allowed to stand at 60 ,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature. | 60 ,90%RH 96hrs | 1,2 |
| Thermal shock resistance | The sample should be allowed stand the following 10 cycles of operation -20 25 70 | -20 /70 10 cycles | |
| Vibration test | Endurance test applying the vibration during transportation and using. | Total fixed amplitude : 1.5mm Vibration Frequency : 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes | 3 |
| Static electricity test | Endurance test applying the electric stress to the terminal. | VS=800V,RS=1.5kΩ CS=100pF 1 time | |

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

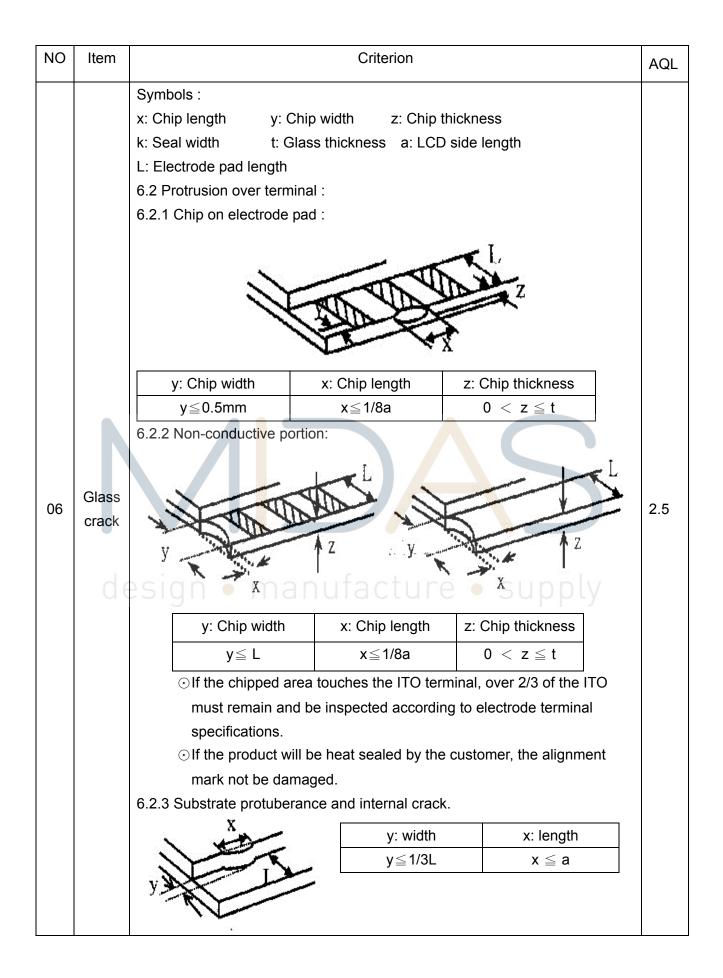
Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

11.Inspection specification

| NO | Item | | Criterion | | AQL |
|----|--|--|--|---|------|
| 01 | Electrical Testing | 1.1 Missing vertical, horizodefect. 1.2 Missing character, do 1.3 Display malfunction. 1.4 No function or no disp 1.5 Current consumption of 1.6 LCD viewing angle de 1.7 Mixed product types. 1.8 Contrast defect. | t or icon. lay. exceeds product sp | | 0.65 |
| 02 | Black or white spots on LCD (display only) | 2.1 White and black spotsthree white or black sp2.2 Densely spaced: No n | oots present. | | 2.5 |
| 03 | LCD black spots, white spots, contamination | 3.2 Line type : (As following | Φ ≤ 0.10 0.10 < Φ ≤ 0.20 0.20 < Φ ≤ 0.25 0.25 < Φ | Acceptable Q TY Accept no dense 2 1 0 | 2.5 |
| | (non-display) | $\begin{array}{c c} & Length \\ \hline \\ \hline \\ \hline \\ \hline \\ \\ \hline \\ \\ \\ \\ \\ \\ \\ \\ $ | Width W \leq 0.02 0.02 < W \leq 0.03 0.03 < W \leq 0.05 0.05 < W | Acceptable Q TY Accept no dense 2 As round type | 2.5 |
| 04 | Polarizer bubbles | If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction. | Size Φ Φ \leq 0.20 0.20<Φ \leq 0.50 0.50<Φ \leq 1.00 1.00<Φ | Acceptable Q TY Accept no dense 3 2 0 3 3 | 2.5 |

| 05 Scratches Follow NO.3 LCD black spots, white spots, contamination Symbols Define: x: Chip length y: Chip width z: Chip thickness x: Chip length y: Chip width z: Chip thickness a: LCD side length L: Electrode pad length: 6.1 General glass chip : 6.1.1 Chip on panel surface and crack between panels: 06 Chipped glass z: Chip thickness y: Chip width x: Chip length 06 Chipped glass 1/2t < z ≤ 2t Not over viewing x ≤ 1/8a 2.5 06 Chipped glass 0: If there are 2 or more chips, x is total length of each chip. 2.5 06 6.1.2 Corner crack: Ufficiency y y y | NO | Item | | Criterion | | AQL |
|--|----|------------------|--|---|---|-----|
| $\begin{array}{ c c c c c c } & \text{Chip length} & y: \text{Chip width} & z: \text{Chip thickness} \\ & \text{K: Seal width} & \text{t: Glass thickness} & a: \text{LCD side length} \\ & \text{L: Electrode pad length:} \\ \hline & \text{6.1 General glass chip :} \\ \hline & \text{6.1.1 Chip on panel surface and crack between panels:} \\ \hline & \hline$ | 05 | Scratches | Follow NO.3 LCD black | spots, white spots, con | Itamination | |
| z: Chip thicknessy: Chip widthx: Chip length $Z \le 1/2t$ Not over viewing $x \le 1/8a$ $1/2t < z \le 2t$ Not exceed $1/3k$ $x \le 1/8a$ | | Chipped glass | Symbols Define:x: Chip lengthy:k: Seal widtht: CL: Electrode pad length6.1 General glass chip6.1.1 Chip on panel sur $I = 1 + 1 + 1 + 1 + 1 + 1 + 1 + 1 + 1 + 1$ | Chip width z: Chip Glass thickness a: LCI face and crack betweer y: Chip width Not over viewing area Not exceed 1/3k chips, x is total length ufacture y: Chip width Not over viewing area | thickness D side length n panels: x: Chip length $x \le 1/8a$ of each chip. Supply y x: Chip length $x \le 1/8a$ | 2.5 |



| NO | Item | Criterion | AQL | | | |
|----|-----------------------|--|---|--|--|--|
| 07 | Cracked glass | The LCD with extensive crack is not acceptable. | | | | |
| 08 | Backlight elements | 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. | | | | |
| 09 | Bezel | 9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications. | | | | |
| 10 | PCB · COB desig | 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB X * Y<=2mm2 | 2.5 2.5 0.65 2.5 0.65 0.65 0.65 2.5 2.5 2.5 2.5 | | | |
| 11 | Soldering | 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. | 2.5 2.5 2.5 0.65 | | | |

| NO | Item | Criterion | | | |
|----|-----------------------|---|------|--|--|
| | General appearance | 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. | | | |
| | | 12.2 No cracks on interface pin (OLB) of TCP. | 0.65 | | |
| | | 12.3 No contamination, solder residue or solder balls on product. | 2.5 | | |
| | | 12.4 The IC on the TCP may not be damaged, circuits. | | | |
| | | 12.5 The uppermost edge of the protective strip on the interface | 2.5 | | |
| | | pin must be present or look as if it cause the interface pin to | | | |
| | | sever. | 2.5 | | |
| 12 | | 12.6 The residual rosin or tin oil of soldering (component or chip | | | |
| | | component) is not burned into brown or black color. | | | |
| | | 12.7 Sealant on top of the ITO circuit has not hardened. | 0.65 | | |
| | | 12.8 Pin type must match type in specification sheet. 12.9 LCD pin loose or missing pins. | | | |
| | | | | | |
| | | 12.10 Pr <mark>o</mark> duct packaging must the same as specified on | 0.65 | | |
| | | packaging specification sheet. 12.11 Product dimension and structure must conform to product | | | |
| | | | | | |
| | | spe <mark>cif</mark> ication sheet. | | | |
| | | 12.12 Visual defect outside of VA is not considered to be rejection. | | | |

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12.Precautions in use of LCD Modules

- (1)Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6)Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8) T aaæ have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors,capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) A taxe have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, T are have the right to modify the version.)

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13.Material List of Components for RoHs

- 1. A a a hereby declares that all of or part of products (with the mark
 - "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A : The Harmful Material List

| Material | (Cd) | (Pb) | (Hg) | (Cr6+) | PBBs | PBDEs | | |
|---|------------|-------------|-------------|-------------|-------------|-------------|--|--|
| Limited Value | 100 ppm | 1000 ppm | 1000 ppm | 1000 ppm | 1000 ppm | 1000 ppm | | |
| About limited value is active according to Dal 10 | | | | | | | | |

Above limited value is set up according to RoHS.

- 2.Process for RoHS requirement :
 - (1) Use the Sn/Ag/Cu soldering surface ; the surface of Pb-free solder is rougher than we used before.
 - (2) Heat-resistance temp. :

Reflow: 250 ,30 seconds Max.;

Connector soldering wave or hand soldering : 320 , 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5 ;

Recommended customer's soldering temp. of connector : 280 $\,$, 3 seconds.

14.Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.

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